

L I M I T E D T E N D E R
N O T I C E

Tender Ref. No.	Date	Tender Due Date
PUR-12/18/2019-MCAD_DIV_SAM_CHENNAI-7181	21.5.2019	04.06.2019

To

Dear Sir,

The Purchase Officer, SAMEER-Centre for Electromagnetics invites sealed tender for the Fabrication of Printed circuit boards (PCB) as per details given below:

Sl. No	Description of Items	Qty (Nos.)
1.	16x4 lens loaded switched beam antenna (Specification list Attached)	2
2.	Rotman lens antenna (Specification list attached)	2

Terms and Conditions

- Price quoted should be on the basis of Destination delivery at Perungudi Campus, Chennai- 600 096.
- Delivery / Completion period should be clearly indicated.
- Excise Duty, GST Percentage should be clearly indicated if admissible. Not eligible for FORM 'C' / 'D'
- WE ARE EXEMPTED FROM EXCISE DUTY
- Quotation should be valid for atleast 60 days from the date of opening of the tender
- Quotation should be sent in sealed envelope super scribing the tender reference number and tender due date. YOUR OFFER WILL NOT BE CONSIDERED IF OUR TENDER REFERENCE NO. & TENDER DUE DATE IS NOT MENTIONED ON COVER.
- Late tenders will not be accepted under any circumstances
- We reserve the right to accept or reject any quotations fully or partly without assigning any reasons.
- For Further Clarification Please Contact 044-22544061 / 22544020
Email: purchase.chn.sameer@nic.in
- Unsolicited bids shall not be considered


(P.Ramamoorthi)
Head – Administration
Contd..

Required specifications for lens loaded switched beam array:

S.No	Specification		Compliance
1.	Board Thickness	0.7155 mm(Approximate)	
2.	Via Requirements	Through hole	
		Blind via(From L1 to L2)	
		Buried via (NIL)	
3.	Via hole size		
	a. Minimum hole size-	Mechanical - 0.35mm	
	b. Maximum hole size	Mechanical - 4mm	
	c. Number of holes	Approximately 2800	
4.	Number of Copper layers	Four	
5.	Substrate Material(Top)	Rogers RO4003C , 8 mils	
6.	Prepreg material	Rogers RO4450 , 8 mils final thickness	
7.	Substrate Material(Bottom)-	Rogers RO4003C , 8 mils	
8.	Board Size	250*250 mm (Approx)	
9.	Minimum Track With	0.3mm	
10.	Minimum gap	0.18mm	
11.	Board overall thickness tolerance	< +/- 10%	
12.	Solder mask	Only on -Top Layer	
13.	Surface finiss	ISIG / ENIPIG / ENEPIG	
14.	Copper thickness	35 microns for L1 and L4	
		18 microns for L2 and L3	
15.	Solder mask color	Green	
16.	Silk screen	Required	
17.	ROHS compliance	Required	
18.	Via on pad	Not available	
19.	Via filling	Not required	
20.	Edge plating	Not required	
21.	PCB type	industrial grade	
22.	Fabrication file format	Gerber files RS-274X format	
23.	Impedance Control	Required	
24.	Electrical testing	Required	
25.	Number of boards required-	Minimum 2 numbers	

Required specifications for Rotman lens PCB fabrication:

S.No	Specification		Compliance
1.	Board Thickness	1.27 mm(Approximate)	
2.	Via Requirements	Through hole	
		Blind via(From L1 to L2)	
		Buried via (NIL)	
3.	Via hole size		
	a. Minimum hole size-	Mechanical - 0.35mm	
	b. Maximum hole size	Mechanical - 4mm	
	c. Number of holes	Approximately 1400	
4.	Number of Copper layers	Four	
5.	Substrate Material(Top)	RT/Duroid 5880,10mil	
6.	Prepreg material	FR4 (26 mil) (Final Thickness)	
7.	Substrate Material(Bottom)-	FR4,10 mil	
8.	Board Size	200*310 mm (Approx)	
9.	Minimum Track With	0.15 mm	
10.	Minimum gap	0.18 mm	
11.	Board overall thickness tolerance	< +/- 10%	
12.	Solder mask	Only on - Top Layer	
13.	Surface finish	ISIG / ENIPIG / ENEPIG	
14.	Copper thickness	35 microns for L1 and L4	
		18 microns for L2 and L3	
15.	Solder mask color	Green	
16.	Silk screen	Required	
17.	ROHS compliance	Required	
18.	Via on pad	Not available	
19.	Via filling	Not required	
20.	Edge plating	Not required	
21.	PCB type	industrial grade	
22.	Fabrication file format	Gerber files RS-274X format	
23.	Impedance Control	Required	
24.	Electrical testing	Required	
25.	Number of boards required-	Minimum 2 numbers	